



## Process Change Notification (PCN)

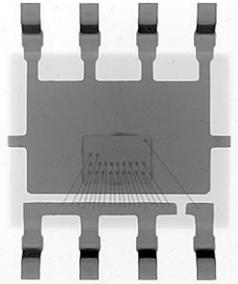
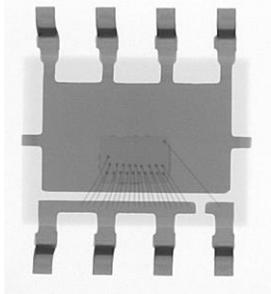
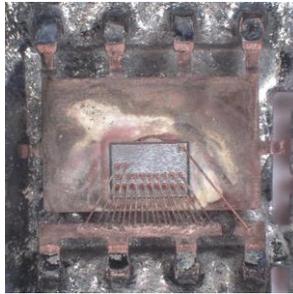
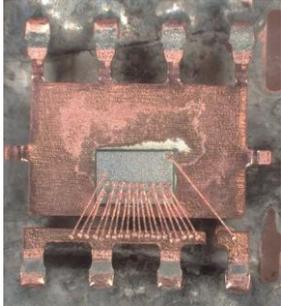
This Product Change Notification (PCN) is issued to inform customers of changes to the products listed below manufactured by Micro Commercial Components Corp. (MCC).

|   |  |
|---|--|
| <b>Notification number:</b>               | PCN-030626-1   |
| <b>PCN Title:</b>                         | Additional new 2nd source  |
| <b>Issue date:</b>                        | 3/6/2026   |
| <b>Proposed effective date:</b>           | 6/6/2026   |
| <b>Product type affected:</b>             | Please refer to table 1 in Appendix 1&table 1 in Appendix 2.   |
| <b>Change Category:</b>                   | Wafer Fab Change   |
| <b>Change Sub-category(s):</b>            | Additional wafer source  |
| <b>Change Classification:</b>             | Major  |
| <b>Change description and reason:</b>     | An additional wafer source has been qualified to ensure business continuity. Full electrical characterization and high-reliability testing have been completed, with no changes to device marking or datasheet specifications.   |
| <b>Deposition of old product:</b>         | Existing inventory will continue to ship until stock is depleted.  |
| <b>Identification of Changed product:</b> | <input type="checkbox"/> Body Marking <input checked="" type="checkbox"/> Lot code <input type="checkbox"/> Datasheet Revision<br><input type="checkbox"/> Labelling <input type="checkbox"/> Reel/packaging <input type="checkbox"/> Not Applicable<br><input type="checkbox"/> Date Code    identification |
| <b>Contact Information:</b>               | Please contact your respective MCC Account Manager (AM) / Inside Sales Representative (ISR/CSR)  |
| <b>Approved by:</b>                       | Seaman Wu (Director of Quality)<br>TH Koay (Head of Product BU)<br>Steve Zhang (Director of Supply Chain)<br>Pamela Cheng (GM & EVP of Sales)  |

## Appendix 1: Table 1

| List of affected products |                 |               |                |
|---------------------------|-----------------|---------------|----------------|
| MCQ18N03-TP               | MCACD6D5N03L-TP | MCG50N03-TP   | MCU80N03A-TP   |
| MCU50N06A-TP              | MCAC10H03A-TP   | MCQ16N03-TP   | MCQ4406A-TP    |
| MCQD12N03A-TP             | MCM13N03-TP     | MCG6D5N03L-TP | MCU50N03A-TP   |
| MCAC50N03-TP              | MCU80N03-TP     | MCAC40N03A-TP | MCG30N03A-TP   |
| MCGD25N04-TP              | MCG35N04A-TP    | MCU60N04A-TP  | MCAC7D0N04L-TP |
| MCG20N04-TP               | MCM012N04L-TP   | MCQD05N06-TP  | MCA031N06L-TP  |
| MCT05N06-TP               | MCQ4438-TP      | MCU20N06A-TP  | MCU20N06B-TP   |
| MCU20N06B-TPA01           | MCAC30N06Y-TP   |               |                |

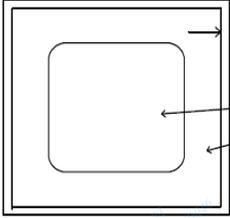
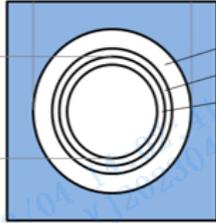
## Table 2: Structure Comparison

| MPN                                | Item  | Existing Source  | New Source  |
|------------------------------------|-------|--|---|
| Representative PN :<br>MCQ16N03-TP | X-ray |  |  |
|                                    | Decap |  |  |

## Appendix 2: Table 1

| No. | Product type | Existing marking | New marking | Package type/code |
|-----|--------------|------------------|-------------|-------------------|
| 1   | RB500V-40-TP | 2                | No change   | SOD-323           |

## Table 2: Chip Comparison

| Item       | Existing source  | New source   |
|------------|--|--|
| Appearance |  |  |
| Die Size   | 0.35*0.35mm  | 0.28*0.28mm  |

## Reliability Data Summary:

Representative Part Number: MCQ16N03-TP

Date: 2026-2-20

Test Results: PASS

| Test Item   | Conditions  | Duration                                      | Quantity  | Rejects   |
|---|---|---|-----------|-----------|
| <b>TEST</b><br>Pre- and Post-Stress<br>Electrical Test        | T <sub>a</sub> = 25 °C  | N/A   | all parts | see below |
| * <b>Pre-conditioning<br/>for MSL 1</b>                       | JESD22A-113<br>1. Temperature Cycling: -40 °C ~60 °C<br>2. Bake: 125 °C,<br>3. Moisture Soak: 85 °C, 85%RH for MSL1,<br>4. Reflow*3cycles: 260 °C | 5 cycles<br>24 hours<br>192 hours<br>3 Cycles | 261 Pcs   | 0         |
| <b>HTRB</b><br>High Temperature<br>Reverse Bias               | MIL-STD-750<br>Method 1038<br>T <sub>j</sub> = T <sub>jmax</sub> , 100% VR  | 1000 hours                                    | 77 Pcs    | 0         |
| <b>HTGB</b><br>High Temperature<br>Reverse Bias               | JESD22-A108<br>T <sub>j</sub> = T <sub>jmax</sub> , 100% VGS  | 1000 hours                                    | 77 Pcs    | 0         |
| <b>TC</b><br>Temperature Cycling                              | JESD22-A104<br>55 °C (+0,-10)/15Min~<br>150(+15,-0)/15Min   | 1000 Cycles<br>(500 hours)                    | 77 Pcs    | 0         |
| <b>UHASt</b><br>Unbiased Highly<br>Accelerated Stress         | JESD22-A118<br>T <sub>a</sub> = 130 °C ±2 °C, RH = 85% ±5%,   | 48 hours                                      | 77 Pcs    | 0         |
| <b>HAST</b><br>High Humidity High<br>Temperature Reverse Bias | 130 ± °C, 85% ±5% RH,<br>80% VR (Max=42V)   | 96 hours                                      | 77 Pcs    | 0         |
| <b>RSH</b><br>Resistance to Solder Heat                       | JESD22-B106<br>260 °C (+5, -0)  | 10 s  | 30 Pcs    | 0         |
| <b>SD</b><br>Solderability                                    | J-STD-002<br>245 °C ± 5 °C  | 3 s   | 10 Pcs    | 0         |

\*Remark : detail MSL of product refer to data sheet on MCC website.

## Reliability Data Summary:

Part Number: RB500V-40-TP

Date: 2025-12-12

Test Results: PASS

| Test Item  | Conditions   | Duration                                     | Quantity  | Rejects   |
|--|--|--|-----------|-----------|
| <b>TEST</b><br>Pre- and Post-Stress<br>Electrical Test         | T <sub>a</sub> = 25 °C   | N/A  | all parts | see below |
| * <b>Pre-conditioning for MSL 1</b>                            | JESD22A-113<br>1. Temperature Cycling: -40 °C ~ 60 °C,<br>2. Bake: 125 °C,<br>3. Moisture Soak: 85 °C, 85% RH for MSL1;<br>4. Reflow*3Cycles: 260 °C | 5Cycles;<br>24 hours;<br>192hours<br>3Cycles | 308Pcs    | 0         |
| <b>HTRB</b><br>High Temperature<br>Reverse Bias                | MIL-STD-750<br>Method 1038<br>T <sub>j</sub> = T <sub>jmax</sub> , 80% VR  | 1000 hours                                   | 77Pcs     | 0         |
| <b>TC</b><br>Temperature Cycling                               | JESD22-A104<br>-55 °C (+0,-10)/15Min~<br>125(+15,-0)/15Min,  | 1000Cycles<br>(500hours)                     | 77Pcs     | 0         |
| <b>AC</b><br>Autoclave   | JESD22-A102<br>T <sub>a</sub> = 121 °C±2 °C, RH = 100 %, 15psig  | 96 hours                                     | 77Pcs     | 0         |
| <b>H3TRB</b><br>High Humidity High<br>Temperature Reverse Bias | JESD22-A101<br>T <sub>a</sub> = 85 °C±2 °C, RH = 85%±5%, 80 % VR (VR MAX=100V)   | 1000 hours                                   | 77Pcs     | 0         |
| <b>RSH</b><br>Resistance to Solder Heat                        | JESD22-B106<br>260 °C (+5, -0)   | 10 s   | 30Pcs     | 0         |
| <b>SD</b><br>Solderability                                     | J-STD-002<br>235 °C ± 5 °C   | 3 s  | 10Pcs     | 0         |

\*Remark : detail MSL of product refer to data sheet on MCC website.



Micro Commercial Components

## Product Change Notification

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**Date: 3/6/2026**

**PCN #: PCN- 030626-1**

**PCN Title: Additional new 2nd source**

Dear Customer,

This Product Change Notification (PCN) is issued to inform customers of changes affecting the above-mentioned product(s) offered by Micro Commercial Components Corp. (MCC).

Customers are requested to acknowledge receipt of this notification within **30 days** from the issue date of this PCN by contacting their local ISR/CSR or sales representative.

If product samples are required for evaluation purposes, please submit a corresponding request within 30 days of this notification.

If you have any questions, require clarification, or need additional support regarding this PCN, please contact your local Account Manager (AM), CSR, or ISR.

Yours sincerely,

MCC PCN Team